



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



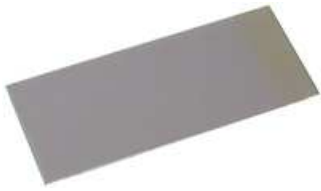
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HSP-7

- Thermal Pad suitable for NOVA22 Panel Mount SSRs
- Easy to use thermal interface material
- Excellent alternative to thermal grease

TYPICAL PROPERTIES

Description	Parameters
Material	Chomerics T725
Color	Pink
Thickness [inch (mm)]	0.005 (0.127)
Adhesive	No
Thermal Impedance [$^{\circ}\text{C}\text{-in}^2/\text{W}$] (1)	0.06 @ 25 psi
Thermal Conductivity [$\text{W}/\text{m}\text{-K}$] (1)	0.07
Flame Rating	V0
Continuous Temperature Range [$^{\circ}\text{C}$]	-55 to 125
Volume Resistivity [$\text{Ohm}\text{-cm}$]	$> 10^4$

MOUNTING SURFACE PREPARATION

The mounting surface, usually the heat sink, should be clean and free from machining oils and aluminum dust, and may be cleaned with any common solvent, such as isopropyl alcohol (IPA) if necessary. The surface of the heat sink may be anodized, chromate coated or unfinished aluminum.

INSTALLATION OF HSP-7 PADS

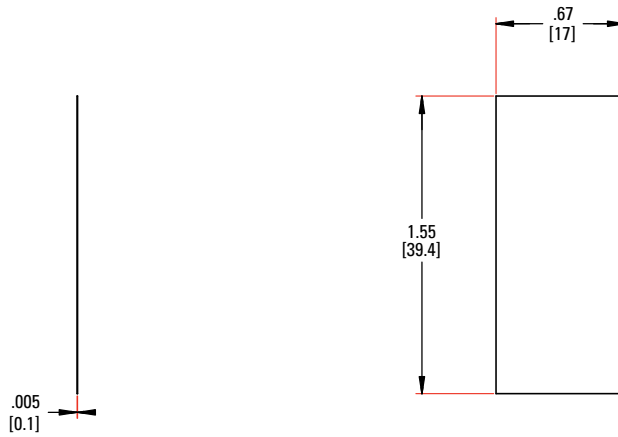
HSP-7 material does not require pre-heating of the heat sink prior to installing the HSP-7 pad onto the heat sink, because of the phase change nature of the HSP-7 material, please follow the process temperature/pressure guidelines below to ensure the best results for a specific assembly process:

Temperature/Pressure	
Process Step	Recommended Range
Removing pad from clear carrier liner	Temp. of Roll: less than 38°C (100°F)
Installing pad onto "cold" heat sink	Heat Sink Temp: 16°C to 38°C (60°F to 100°F)
	Roll Temp: 21°C to 38°C (70°F to 100°F) Installation Pressure: 25 to 50 psi (2)
Installing pad onto "warm" heat sink	Heat Sink Temp: 24°C to 38°C (75°F to 100°F)
	Roll Temp: 21°C to 38°C (70°F to 100°F) Installation Pressure: 25 to 50 psi (2)
Removing protective blue release liner	Temp of Heat Sink/Pad Assembly: Less than 38°C (100°F)

When removing the pull-tab, use a quick, lifting motion. This is preferable over peeling the pull-tab from the HSP-7 pad and heat sink. To ensure optimal "wetting" of the HSP-7 pad to the heat sink. It is recommended that the parts be allowed to dwell one hour prior to attempting release liner removal.

MECHANICAL SPECIFICATIONS

Tolerances: ± 0.02 in / 0.5 mm
All dimensions are in: inches [Millimeters]



GENERAL NOTES

- (1) This value is provided for reference only. Follow installation instructions for accurate thermal performance.
- (2) Apply pressure to the HSP-7 pad with a soft "press-pad" for 2 to 3 seconds.

ANNEX - ENVIROMENTAL INFORMATION

The environmental information disclosed in this annex including the EIP Pollution logo are in compliance with People’s Republic of China Electronic Industry Standard SJ/T11364 – 2006, Marking for Control of Pollution Caused by Electronic Information Products.

Part Name	Toxic or hazardous Substance and Elements					
	Lead (Pb)	Mercury (Hg)	Cadmium (Cd)	Hexavalent Chromium (Cr (VI))	Polybrominated biphenyls (PBB)	Polybrominated diphenyl ethers (PBDE)
Semiconductor die	X	O	O	O	O	O
Solder	X	O	O	O	O	O

附件 - 环保信息

此附件所标示的包括电子信息产品污染图标的环保信息符合中华人民共和国电子行业标准 SJ/T 11364 - 2006, 电子信息产品污染控制标识要求。

部件名称	有毒有害物质或元素					
	铅 (Pb)	汞 (Hg)	镉 (Cd)	六价铬 (Cr (VI))	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
半导体芯片	X	O	O	O	O	O
焊接点	X	O	O	O	O	O

